

LM2936-5.0EP Enhanced Plastic Ultra-Low Quiescent Current 5V Regulator

Check for Samples: [LM2936-5.0EP](#)

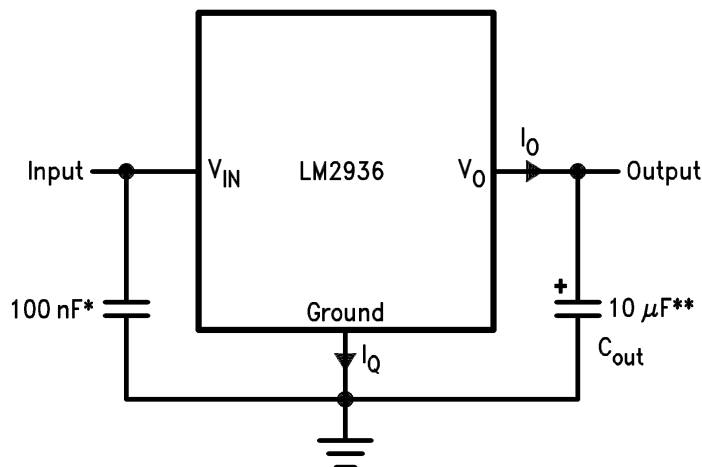
FEATURES

- Ultra Low Quiescent Current ($I_Q \leq 15 \mu\text{A}$ for $I_O = 100 \mu\text{A}$)
- Fixed 5V, 50 mA Output
- $\pm 2\%$ Initial Output Tolerance
- $\pm 3\%$ Output Tolerance Over Line, Load, and Temperature
- Dropout Voltage Typically 200 mV @ $I_O = 50 \text{ mA}$
- Reverse Battery Protection
- -50V Reverse Transient Protection
- Internal Short Circuit Current Limit
- Internal Thermal Shutdown Protection
- 40V Operating Voltage Limit
- 60V Operating Voltage Limit for LM2936HVEP
- Shutdown Pin Available with LM2936BMEP Package

APPLICATIONS

- Selected Military Applications
- Selected Avionics Applications

TYPICAL APPLICATION



* Required if regulator is located more than 2" from power supply filter capacitor.

** Required for stability. Must be rated for 10 μF minimum over intended operating temperature range. Effective series resistance (ESR) is critical, see curve. Locate capacitor as close as possible to the regulator output and ground pins. Capacitance may be increased without bound.



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DESCRIPTION

The LM2936EP ultra-low quiescent current regulator features low dropout voltage and low current in the standby mode. With less than 15 μA quiescent current at a 100 μA load, the LM2936EP is ideally suited for automotive and other battery operated systems. The LM2936EP retains all of the features that are common to low dropout regulators including a low dropout PNP pass device, short circuit protection, reverse battery protection, and thermal shutdown. The LM2936EP has a 40V maximum operating voltage limit, a -40°C to $+125^\circ\text{C}$ operating temperature range, and $\pm 3\%$ output voltage tolerance over the entire output current, input voltage, and temperature range. The LM2936EP is available in a TO-92 package, a SOIC-8 surface mount package, and a TO-252 surface mount power package.

ENHANCED PLASTIC

- Extended Temperature Performance of -40°C to $+125^\circ\text{C}$
- Baseline Control - Single Fab & Assembly Site
- Process Change Notification (PCN)
- Qualification & Reliability Data
- Solder (PbSn) Lead Finish is Standard
- Enhanced Diminishing Manufacturing Sources (DMS) Support

CONNECTION DIAGRAMS

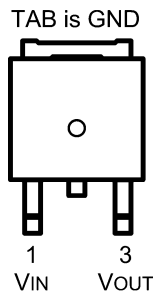


Figure 1. TO-252 (Top View)
See Package Number NDP0003B

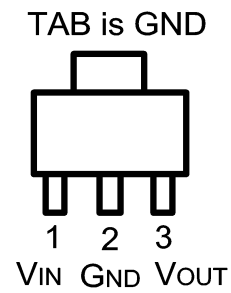


Figure 2. SOT-223 (Top View)
See Package Number MA04A

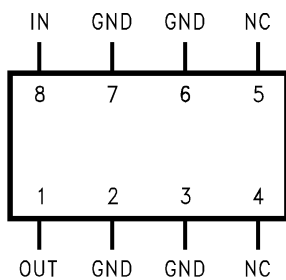


Figure 3. 8-Pin SOIC (D) (Top View)
See Package Number D0008A

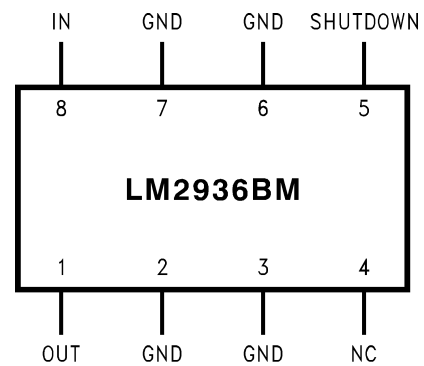


Figure 4. 8-Pin SOIC (D) (Top View)
See Package Number D0008A

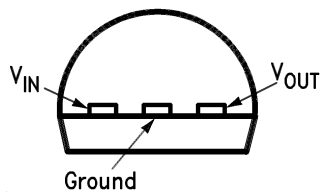


Figure 5. TO-92 (Bottom View)
See Package Number LP0003A

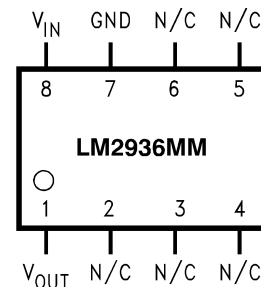


Figure 6. 8-Pin VSSOP (DGK) (Top View)
See Package Number DGK0008A



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾⁽²⁾

Input Voltage (Survival)	+60V, -50V
ESD Susceptibility ⁽³⁾	2000V
Power Dissipation ⁽⁴⁾	Internally limited
Junction Temperature (T _{Jmax})	150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	260°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating ratings.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) Human body model, 100 pF discharge through a 1.5 kΩ resistor.
- (4) The maximum power dissipation is a function of T_{Jmax}, θ_{JA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{Jmax} - T_A)/θ_{JA}. If this dissipation is exceeded, the die temperature will rise above 150°C and the LM2936EP will go into thermal shutdown.

OPERATING RATINGS

Operating Temperature Range	-40°C to +125°C
Maximum Operating Input Voltage - LM2936EP	+40V
Maximum Operating Input Voltage - LM2936HVEP only	+60V
Maximum Shutdown Pin Voltage - LM2936BMEP only	0V to 40V
TO-92 (LP0003A) θ _{JA}	195°C/W
VSSOP-8 (DGK0008A) θ _{JA}	200°C/W
SOIC-8 (D0008A) θ _{JA}	140°C/W
SOIC-8 (D0008A) θ _{JC}	45°C/W
TO-252 (NDP0003B) θ _{JA}	136°C/W
TO-252 (NDP0003B) θ _{JC}	6°C/W
SOT-223 (MA04A) θ _{JA}	149°C/W
SOT-223 (MA04A) θ _{JC}	36°C/W

ELECTRICAL CHARACTERISTICS

$V_{IN} = 14V$, $I_O = 10\text{ mA}$, $T_J = 25^\circ\text{C}$, unless otherwise specified. **Boldface** limits apply over entire operating temperature range

Parameter	Conditions	Min ⁽¹⁾	Typical ⁽²⁾	Max ⁽¹⁾	Units
LM2936HVEP Only					
Output Voltage	$5.5V \leq V_{IN} \leq 48V$, $100\ \mu\text{A} \leq I_O \leq 50\text{ mA}$ ⁽³⁾	4.85	5.00	5.15	V
Line Regulation	$6V \leq V_{IN} \leq 60V$, $I_O = 1\text{ mA}$		15	35	mV
All LM2936EP					
Output Voltage	$5.5V \leq V_{IN} \leq 26V$, $100\ \mu\text{A} \leq I_O \leq 50\text{ mA}$ ⁽³⁾	4.90 4.85	5.00	5.10 5.15	V
Quiescent Current	$I_O = 100\ \mu\text{A}$, $8V \leq V_{IN} \leq 24V$		9	15	μA
	$I_O = 10\text{ mA}$, $8V \leq V_{IN} \leq 24V$		0.20	0.50	mA
	$I_O = 50\text{ mA}$, $8V \leq V_{IN} \leq 24V$		1.5	2.5	mA
Line Regulation	$9V \leq V_{IN} \leq 16V$		5	10	mV
	$6V \leq V_{IN} \leq 40V$, $I_O = 1\text{ mA}$		10	30	
Load Regulation	$100\ \mu\text{A} \leq I_O \leq 5\text{ mA}$		10	30	mV
	$5\text{ mA} \leq I_O \leq 50\text{ mA}$		10	30	
Dropout Voltage	$I_O = 100\ \mu\text{A}$		0.05	0.10	V
	$I_O = 50\text{ mA}$		0.20	0.40	V
Short Circuit Current	$V_O = 0V$	65	120	250	mA
Output Impedance	$I_O = 30\text{ mAdc}$ and 10 mArms , $f = 1000\text{ Hz}$		450		$\text{m}\Omega$
Output Noise Voltage	10 Hz–100 kHz		500		μV
Long Term Stability			20		mV/1000 Hr
Ripple Rejection	$V_{\text{ripple}} = 1V_{\text{rms}}$, $f_{\text{ripple}} = 120\text{ Hz}$	-40	-60		dB
Reverse Polarity Transient Input Voltage	$R_L = 500\Omega$, $T = 1\text{ ms}$	-50	-80		V
Output Voltage with Reverse Polarity Input	$V_{IN} = -15V$, $R_L = 500\Omega$		0.00	-0.30	V
Maximum Line Transient	$R_L = 500\Omega$, $V_O \leq 5.5V$, $T = 40\text{ms}$	60			V
Output Bypass Capacitance (C_{OUT}) ESR	$C_{OUT} = 10\ \mu\text{F}$ $0.1\text{ mA} \leq I_{OUT} \leq 50\text{ mA}$	0.3		8	Ω
Shutdown Input – LM2936BMEP Only					
Output Voltage, V_{OUT}	Output Off, $V_{SD} = 2.4V$, $R_{LOAD} = 500\Omega$		0	0.010	V
Shutdown High Threshold Voltage, V_{IH}	Output Off, $R_{LOAD} = 500\Omega$	2.00	1.1		V
Shutdown Low Threshold Voltage, V_{IL}	Output On, $R_{LOAD} = 500\Omega$		1.1	0.60	V
Shutdown High Current, I_{IH}	Output Off, $V_{SD} = 2.4V$, $R_{LOAD} = 500\Omega$		12		μA
Quiescent Current	Output Off, $V_{SD} = 2.4V$, $R_{LOAD} = 500\Omega$ Includes I_{IH} Current		30		μA

- (1) Data sheet min/max specification limits are ensured by design, test, or statistical analysis.
- (2) Typicals are at 25°C (unless otherwise specified) and represent the most likely parametric norm.
- (3) To ensure constant junction temperature, pulse testing is used.

TYPICAL PERFORMANCE CHARACTERISTICS

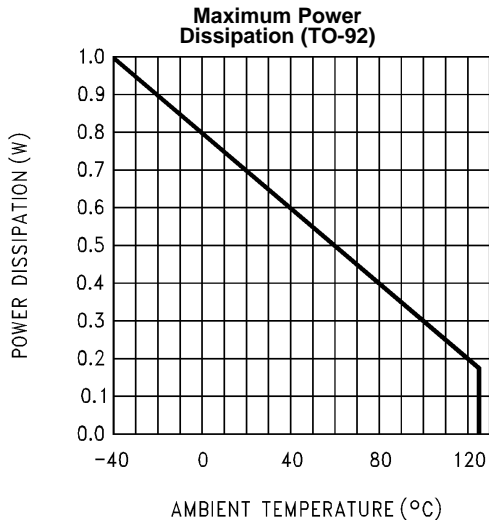


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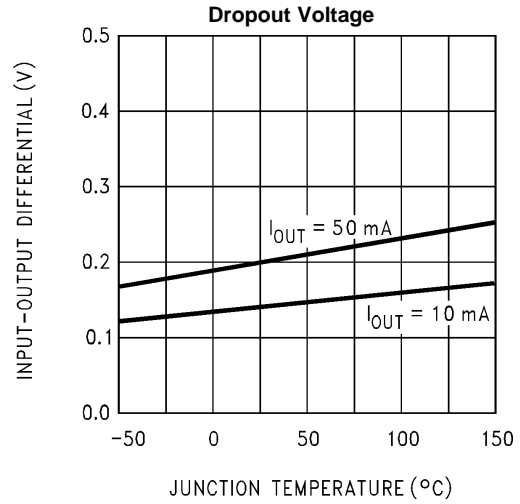


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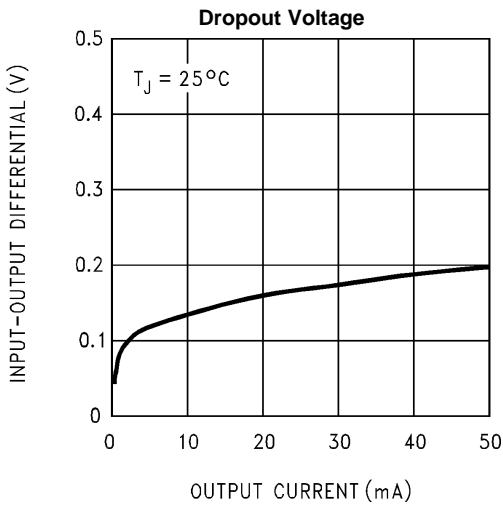


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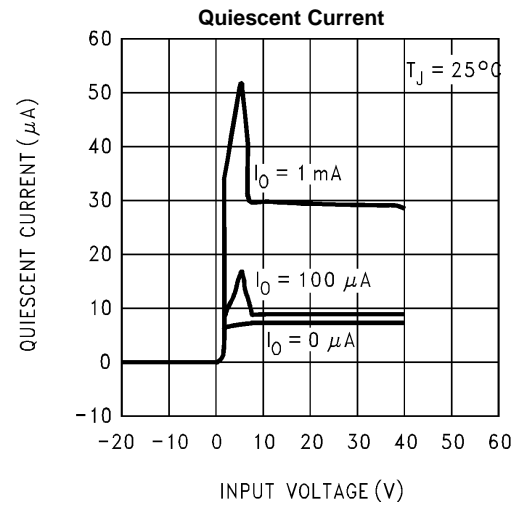


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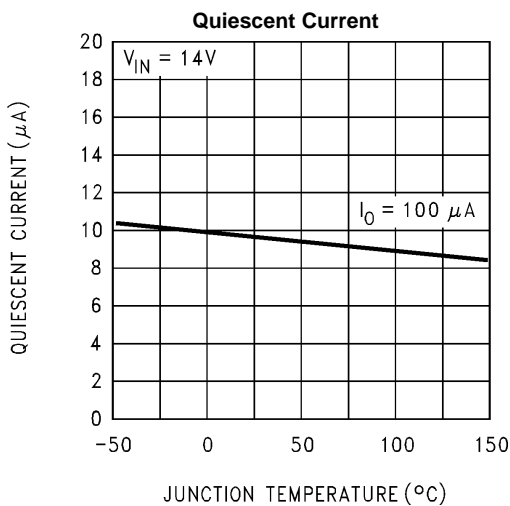


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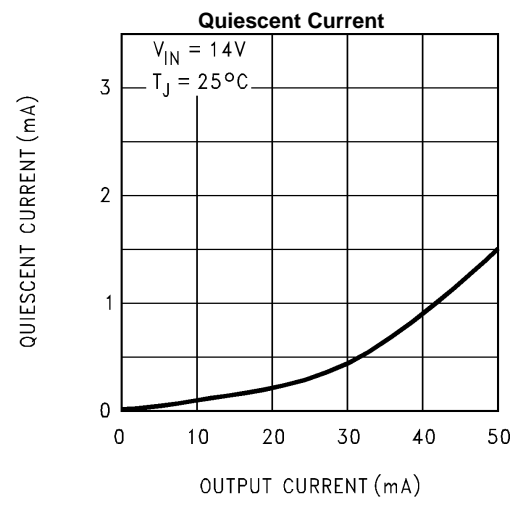


Figure 12.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

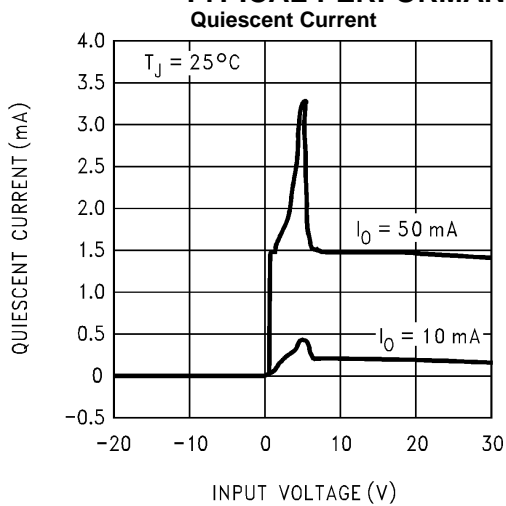


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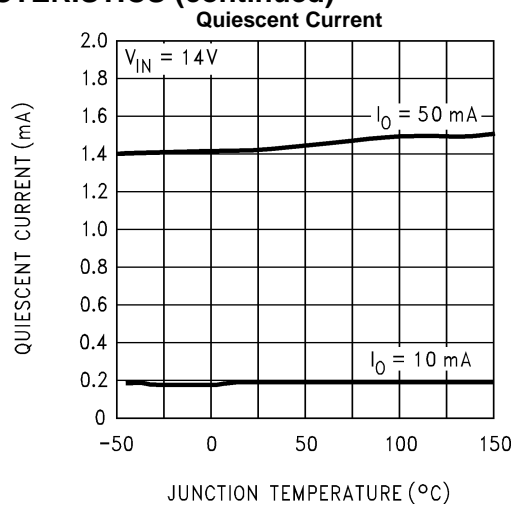


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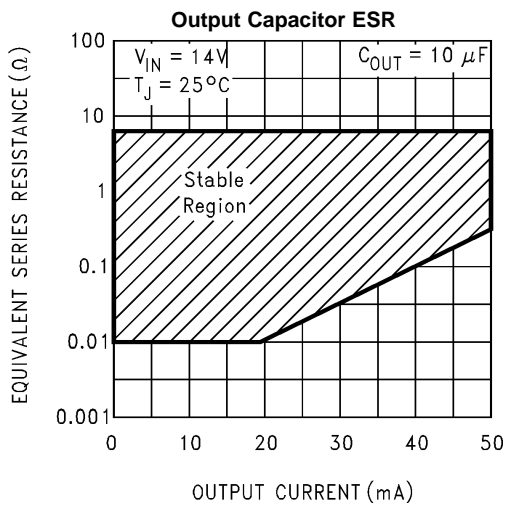


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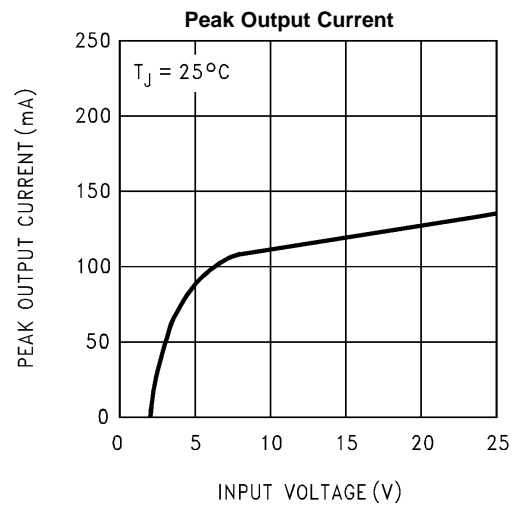


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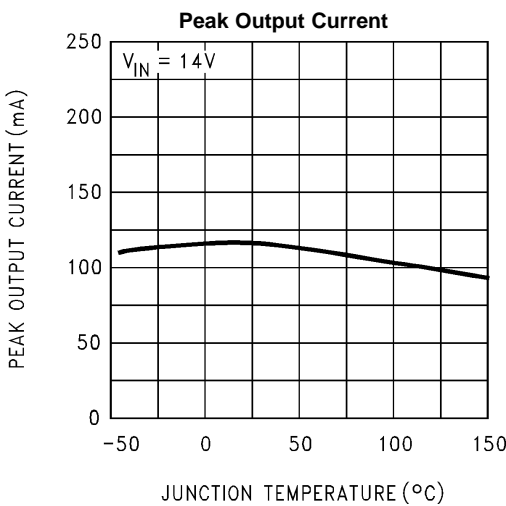


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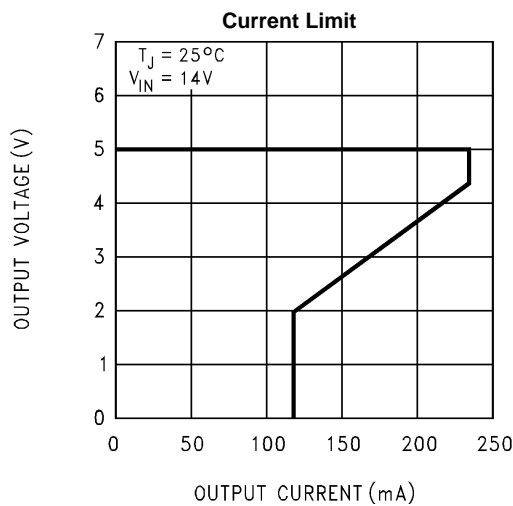


Figure 18.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

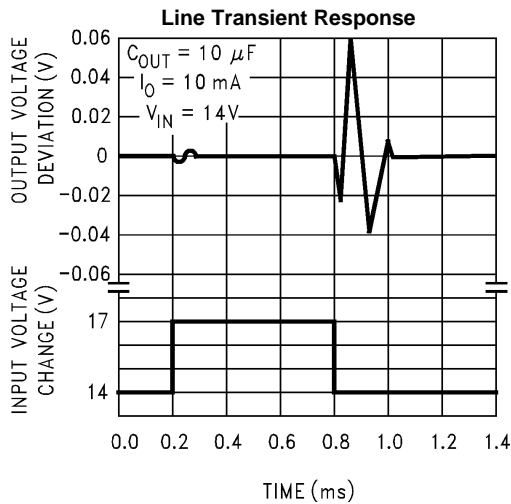


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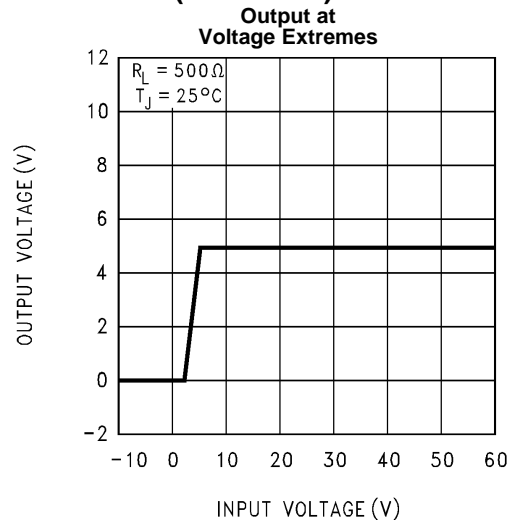


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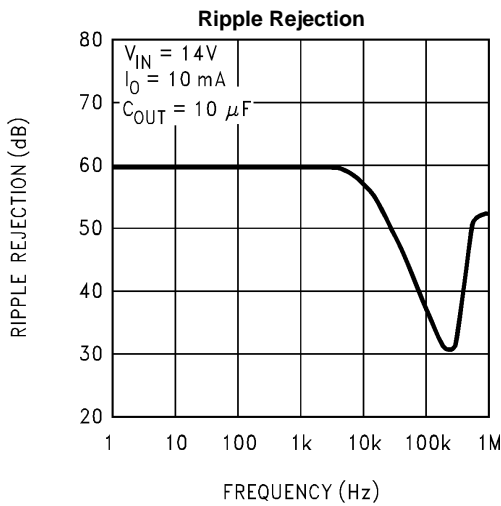


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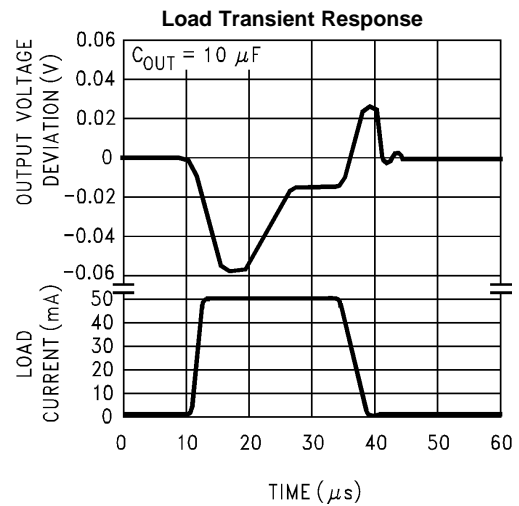


Figure 22.

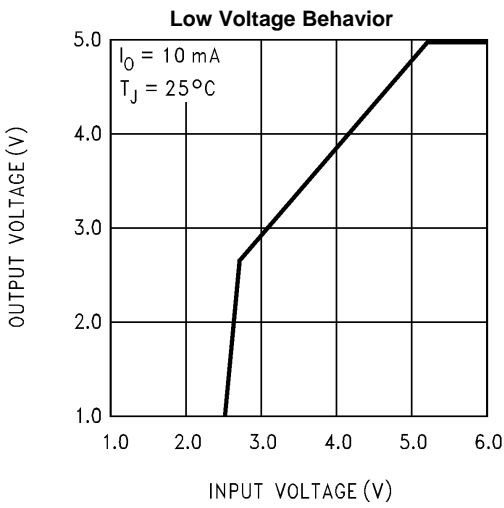


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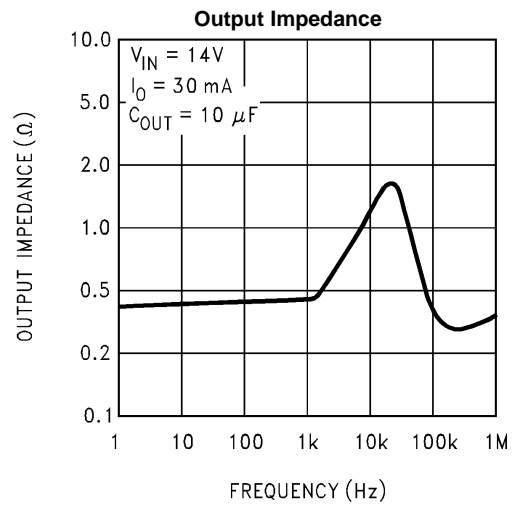


Figure 24.

APPLICATIONS INFORMATION

Unlike other PNP low dropout regulators, the LM2936EP remains fully operational to 40V. Owing to power dissipation characteristics of the available packages, full output current cannot be ensured for all combinations of ambient temperature and input voltage. As an example, consider an LM2936ZEP operating at 25°C ambient. Using the formula for maximum allowable power dissipation (see⁽¹⁾), we find that $P_{Dmax} = 641$ mW at 25°C. Including the small contribution of the quiescent current to total power dissipation the maximum input voltage (while still delivering 50 mA output current) is 17.3V. The LM2936ZEP will go into thermal shutdown if it attempts to deliver full output current with an input voltage of more than 17.3V. Similarly, at 40V input and 25°C ambient the LM2936ZEP can deliver 18 mA maximum.

Under conditions of higher ambient temperatures, the voltage and current calculated in the previous examples will drop. For instance, at the maximum ambient of 125°C the LM2936ZEP can only dissipate 128 mW, limiting the input voltage to 7.34V for a 50 mA load, or 3.5 mA output current for a 40V input.

The junction to ambient thermal resistance θ_{JA} rating has two distinct components: the junction to case thermal resistance rating θ_{JC} ; and the case to ambient thermal resistance rating θ_{CA} . The relationship is defined as: $\theta_{JA} = \theta_{JC} + \theta_{CA}$.

For the SOIC-8 and TO-252 surface mount packages the θ_{JA} rating can be improved by using the copper mounting pads on the printed circuit board as a thermal conductive path to extract heat from the package.

On the SOIC-8 package the four ground pins are thermally connected to the backside of the die. Adding approximately 0.04 square inches of 2 oz. copper pad area to these four pins will improve the θ_{JA} rating to approximately 110°C/W. If this extra pad area is placed directly beneath the package there should not be any impact on board density.

On the TO-252 package the ground tab is thermally connected to the backside of the die. Adding 1 square inch of 2 oz. copper pad area directly under the ground tab will improve the θ_{JA} rating to approximately 50°C/W.

While the LM2936EP has an internally set thermal shutdown point of typically 150°C, this is intended as a safety feature only. Continuous operation near the thermal shutdown temperature should be avoided as it may have a negative affect on the life of the device.

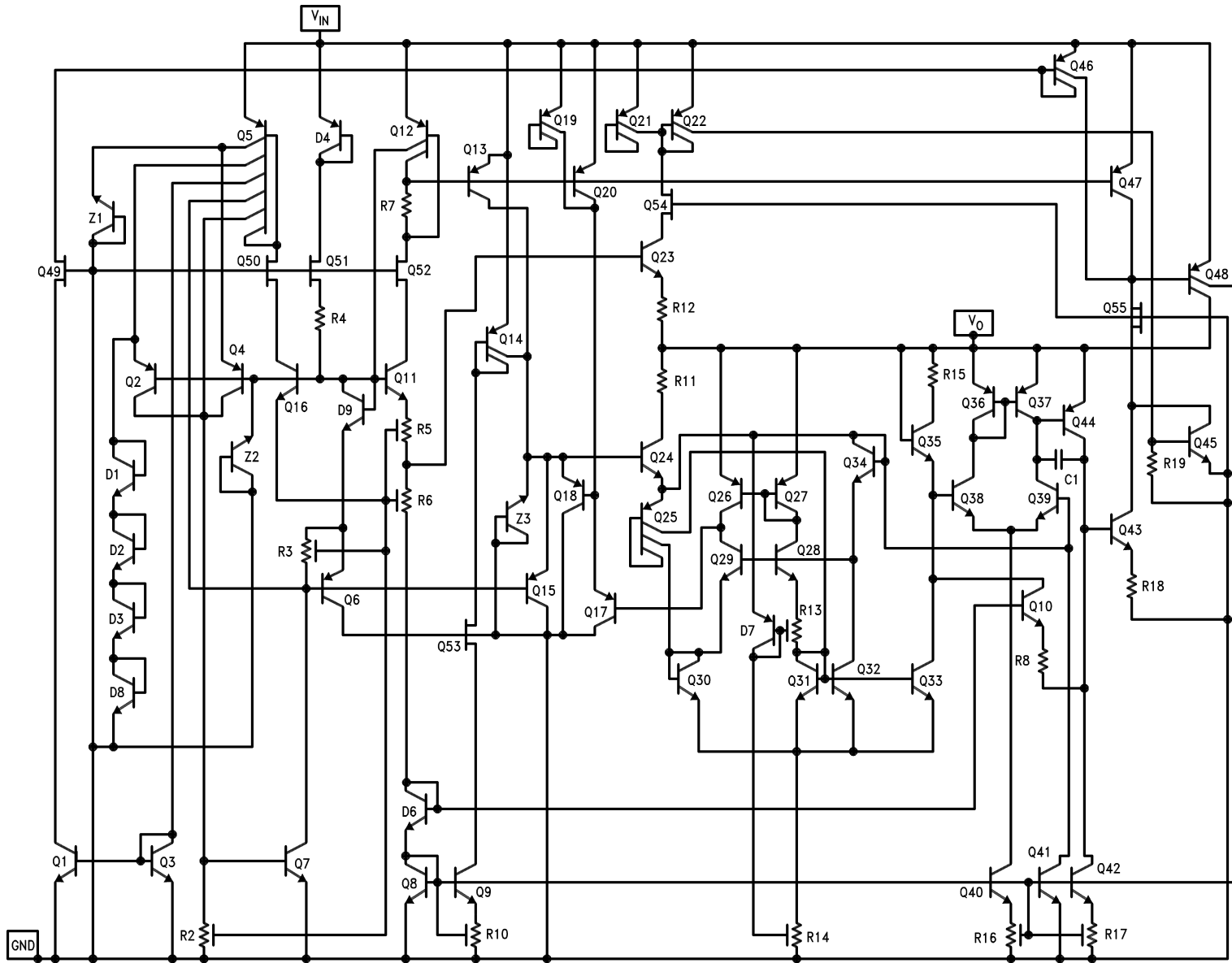
While the LM2936EP maintains regulation to 60V, it will not withstand a short circuit above 40V because of safe operating area limitations in the internal PNP pass device. Above 60V the LM2936EP will break down with catastrophic effects on the regulator and possibly the load as well. Do not use this device in a design where the input operating voltage may exceed 40V, or where transients are likely to exceed 60V.

SHUTDOWN PIN

The LM2936BMEP has a pin for shutting down the regulator output. Applying a Logic Level High (>2.0V) to the Shutdown pin will cause the output to turn off. Leaving the Shutdown pin open, connecting it to Ground, or applying a Logic Level Low (<0.6V) will allow the regulator output to turn on.

(1) The maximum power dissipation is a function of T_{Jmax} , θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{Jmax} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above 150°C and the LM2936EP will go into thermal shutdown.

EQUIVALENT SCHEMATIC DIAGRAM



REVISION HISTORY

Changes from Revision A (April 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format	9

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